● DFN3030-10B Power Dissipation (JESD51-7)

Power dissipation data for theDFN3030-10B is shown in this page.

The value of power dissipation varies with the mount board conditions.

Please use this data as one of reference data taken in the described condition.

1. Measurement Condition (Reference data)

Condition: Mount on a board

Ambient: Natural convection

Soldering: Lead (Pb) free

Board Dimensions: Copper foil 4 layer

dimensions 76.2mm x 114.3mm (about 8700mm^2 in one side)

1st inner layer : No copper foil

2nd inner layer : 70mm x 70mm connection with heat sink

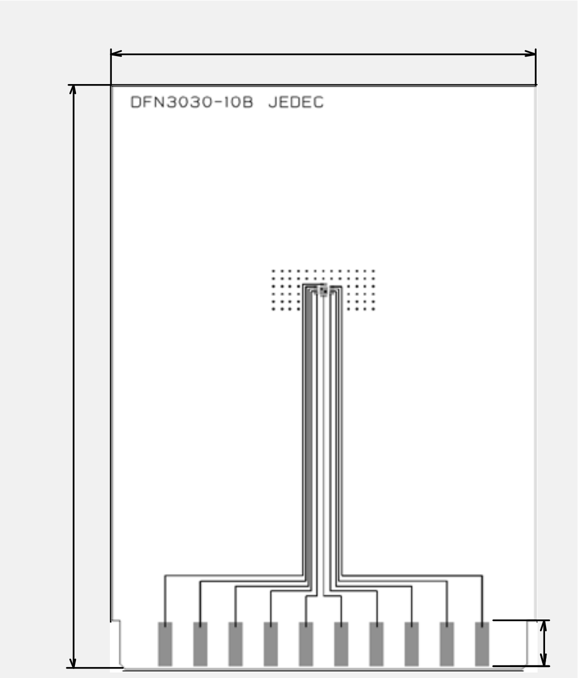
3rd inner layer : 70mm x 70mm connection with heat sink

4th inner layer : No copper foil

Material: Glass Epoxy (FR-4)

Thickness: 1.6 mm

Through-hole: φ0.2mm x 60pcs



Evaluation Board (Unit:mm)

2. Power Dissipation vs. Ambient Temperature

Board Mount (Tjmax=125℃)

Ambient Temperature (℃)	Power Dissipation Pd (mW)	θja(℃/W)
25	1950	51.28
105	390